



DESIGN INFORMATION	
BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)	
<u>2400MIL</u>	X <u>2700</u>
Number of Layers :	<u>4</u>
MIN. TRACK WIDTH:	<u>6</u> MIL
MIN. CLEARANCE:	<u>6</u> MIL
MIN. VIA PAD SIZE:	<u>18</u> MIL
MINIMUM ANNUULAR RING 0.05mm (2MIL) EXTERNAL	
PER IPC-2475 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- <u>5</u> MIL, HOLES +/- <u>3</u> MIL	

MATERIAL: ☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER _____

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)

INNER SIGNAL: ☐ 1.4MIL (1oz) ☒ 2.8MIL (2oz) ☐ N/A

PROCESS _____



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ALTUM DESIGNER VERSION:
24.5.1.21